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("4004195" | "4415025" | "4593342" | "4812978" | "4914551" | "4942076" | "4962416" | "4967950")

U	I	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Retrieval Clas.	Inventor
1	Γ	US 5783862 A	19980721	5	Electrically conductive thermal interface	257/714	165/104.17; 165/185;		Deeney, Jeffrey L.
2	Γ	US 5561323 A	19961001	10	Electronic package with thermally conductive support member having a	257/707	257/706; 257/E21.518;		Andros, Frank E. et al.
3	Γ	US 6522452 A	19960604	18	Liquid cooling system for LSI packages	165/286	165/104.33; 165/295;		Mizuno, Tsukasa et al.
4	Γ	US 5519936 A	19960528	8	Method of making an electronic package with a thermally conductive support	29/840	174/52.4; 174/52.5;		Andros, Frank E. et al.
5	Γ	US 5499450 A	19960319	9	Method of manufacturing a multiple pin heatsink device	29/890.03	165/185; 257/E23.105		Jacoby, John
6	Γ	US 5459352 A	19951017	12	Integrated circuit package having a liquid metal-aluminum/copper joint	257/724	257/713; 257/718;		Layton, Wilber T. et al.
7	Γ	US 5423376 A	19950613	6	Heat exchanger for electronic components and electro-technical	165/80.4	165/186; 165/185;		Julien, Jean-Noel et al.
8	Γ	US 5345107 A	19940906	26	Cooling apparatus for electronic device	257/717	165/185; 257/712;		Daikoku, Takehiro et al.
9	Γ	US 5269372 A	19931214	10	Intersecting flow network for a cold plate cooling system	165/80.4	165/185; 257/714;		Chu, Richard C. et al.
10	Γ	US 5226471 A	19930713	8	Leak isolating apparatus for liquid cooled electronic units in a coolant	165/200	165/103; 165/104.33;		Stefani, Gary G.
11	Γ	US 5060844 A	19911029	7	Interconnection structure and test method	228/180.21	228/203; 228/215;		Behun, John R. et al.
12	Γ	US 4967950 A	19901105	6	Soldering method	228/180.22	228/193; 228/254		Legg, Stephen P. et al.
13	Γ	US 4962416 A	19901009	6	Electronic package with a device positioned above a substrate by suction	257/722	257/783; 257/E23.063;		Jones, Alan L. et al.
14	Γ	US 4942076 A	19900717	11	Ceramic substrate with metal filled via holes for hybrid microcircuits and	428/137	257/E23.067; 257/E23.19;		Panicker, RamaChandra M. P. et al.
15	Γ	US 4914551 A	19900403	7	Electronic package with heat spreader member	361/714	257/713; 257/717;		Anschei, Morris et al.
16	Γ	US 4512978 A	19860923	10	Apparatus for cooling high-density integrated circuit packages	165/104.33	165/46; 257/714;		Cutchaw, John M.
17	Γ	US 4593342 A	19860803	5	Heat sink assembly for protecting pins of electronic devices	361/720	257/718; 257/720;		Lindsay, Paul H.

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